

## DS90CF384AQ +3.3V LVDS Receiver 24-Bit Flat Panel Display (FPD) Link - 65 MHz

Check for Samples: [DS90CF384AQ](#)

### FEATURES

- Automotive Grade Device, AEC-Q100 Grade 3 Qualified
- Operating Temperature Range:  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$
- 20 to 65 MHz Shift Clock Support
- 50% Duty Cycle on Receiver Output Clock
- Best-in-Class Set & Hold Times on RxOUTPUTs
- Rx Power Consumption <142 mW (typ) @65MHz Grayscale
- Rx Power-down Mode <200 $\mu$ W (max)
- ESD Rating >7 kV (HBM), >700V (EIAJ)
- Supports VGA, SVGA, XGA and Dual Pixel SXGA.
- PLL Requires No External Components
- Compatible with TIA/EIA-644 LVDS Standard
- Low Profile 56-Lead TSSOP Package

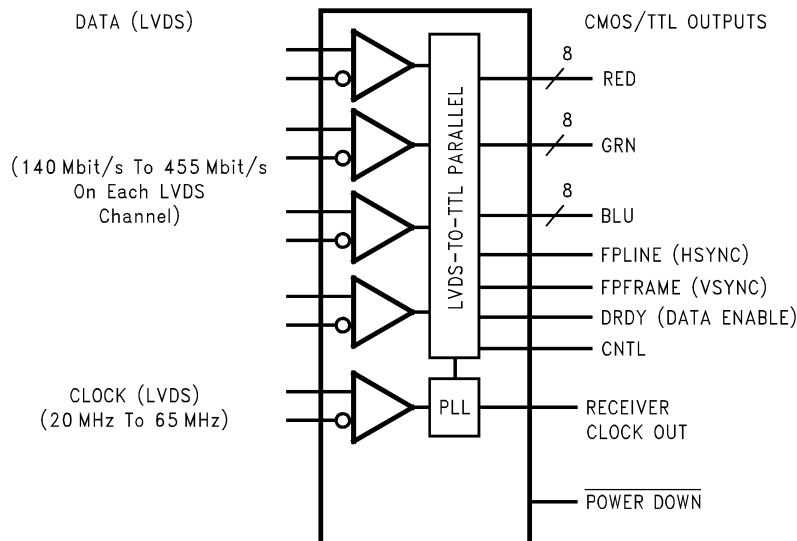
### DESCRIPTION

The DS90CF384AQ receiver converts the four LVDS data streams at up to 1.8 Gbps throughput (227 Megabytes/sec bandwidth) back into parallel 28 bits of LVCMOS/LVTTL data. In a Display application, the 28 bits include: 24 bits of RGB data and up to 4 bits of video control (Hsync, Vsync, DE and CNTL).

The DS90CF384AQ device is enhanced over prior generation FPD-Link receivers, provides a wider data valid time on the receiver output and is offered as an AEC-Q100 grade 3 device.

FPD-Link is an ideal means to solve EMI and cable size problems associated with wide, high speed LVCMOS/LVTTL interfaces.

### Block Diagram



**Figure 1. DS90CF384AQ Block Diagram**



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## Absolute Maximum Ratings<sup>(1)(2)</sup>

Supply Voltage ( $V_{CC}$ )		-0.3V to +4V
LVCMOS/LVTTL Input Voltage		-0.3V to ( $V_{CC} + 0.3V$ )
LVCMOS/LVTTL Output Voltage		-0.3V to ( $V_{CC} + 0.3V$ )
LVDS Receiver Input Voltage		-0.3V to ( $V_{CC} + 0.3V$ )
Junction Temperature		+150°C
Storage Temperature		-65°C to +150°C
For soldering specifications: see <a href="http://www.ti.com/lit/SNOA549">http://www.ti.com/lit/SNOA549</a>		
Maximum Package Power Dissipation Capacity @ 25°C		
DGG Package:		1.61 W
DGG Package Derating:		12.4 mW/°C above +25°C
ESD Rating	(HBM, 1.5 kΩ, 100 pF)	> 7 kV
	(EIAJ, 0Ω, 200 pF)	> 700V

(1) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.

(2) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be ensured. They are not meant to imply that the device should be operated at these limits. The "Electrical Characteristics" specify conditions for device operation.

## Recommended Operating Conditions

	Min	Nom	Max	Units
Supply Voltage ( $V_{CC}$ )	3.0	3.3	3.6	V
Operating Free Air Temperature ( $T_A$ )	-40	+25	+85	°C
Receiver Input Range	0		2.4	V
Supply Noise Voltage ( $V_{CC}$ )			100	mV <sub>PP</sub>

## Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ <sup>(1)</sup>	Max	Units
LVCMOS/LVTTL DC SPECIFICATIONS (For Power Down Pin)						
V <sub>IH</sub>	High Level Input Voltage		2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Low Level Input Voltage		GND		0.8	V
V <sub>CL</sub>	Input Clamp Voltage	I <sub>CL</sub> = -18 mA		-0.79	-1.5	V
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = 0.4V, 2.5V or V <sub>CC</sub>		+1.8	+10	μA
		V <sub>IN</sub> = GND	-10	0		μA
LVCMOS/LVTTL DC SPECIFICATIONS						
V <sub>OH</sub>	High Level Output Voltage	I <sub>OH</sub> = -0.4 mA	2.7	3.3		V
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OL</sub> = 2 mA		0.06	0.3	V
I <sub>OS</sub>	Output Short Circuit Current	V <sub>OUT</sub> = 0V		-60	-120	mA
LVDS RECEIVER DC SPECIFICATIONS						
V <sub>TH</sub>	Differential Input High Threshold	V <sub>CM</sub> = +1.2V			+100	mV
V <sub>TL</sub>	Differential Input Low Threshold		-100			mV
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = +2.4V, V <sub>CC</sub> = 3.6V			±10	μA
		V <sub>IN</sub> = 0V, V <sub>CC</sub> = 3.6V			±10	μA

(1) Typical values are given for  $V_{CC} = 3.3V$  and  $T_A = +25°C$ .

## Electrical Characteristics (continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ <sup>(1)</sup>	Max	Units
<b>RECEIVER SUPPLY CURRENT<sup>(2)</sup></b>						
ICCRW	Receiver Supply Current Worst Case	$C_L = 8\text{ pF}$ , Worst Case Pattern (Figure 2 and Figure 4)	$f = 32.5\text{ MHz}$		49	65 mA
			$f = 37.5\text{ MHz}$		53	70 mA
			$f = 65\text{ MHz}$		81	105 mA
ICCRG	Receiver Supply Current, 16 Grayscale	$C_L = 8\text{ pF}$ , 16 Grayscale Pattern (Figure 3 and Figure 4)	$f = 32.5\text{ MHz}$		28	mA
			$f = 37.5\text{ MHz}$		30	mA
			$f = 65\text{ MHz}$		43	mA
ICCRZ	Receiver Supply Current Power Down	Power Down = Low, Receiver Outputs Stay Low during Power Down Mode		10	55	$\mu\text{A}$

(2) Current into device pins is defined as positive. Current out of device pins is defined as negative. Voltages are referenced to ground unless otherwise specified (except  $V_{OD}$  and  $\Delta V_{OD}$ ).

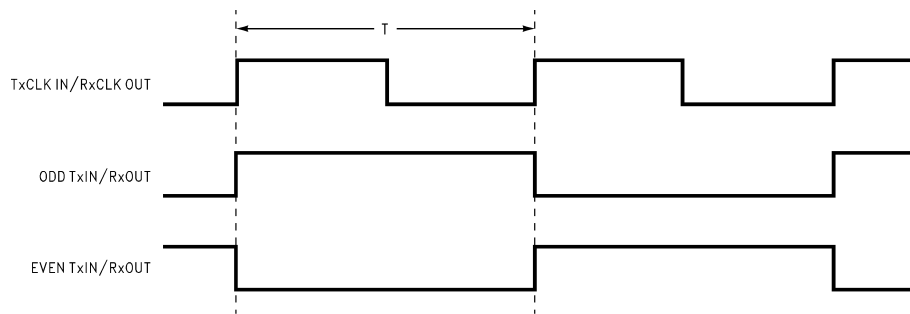
## Receiver Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

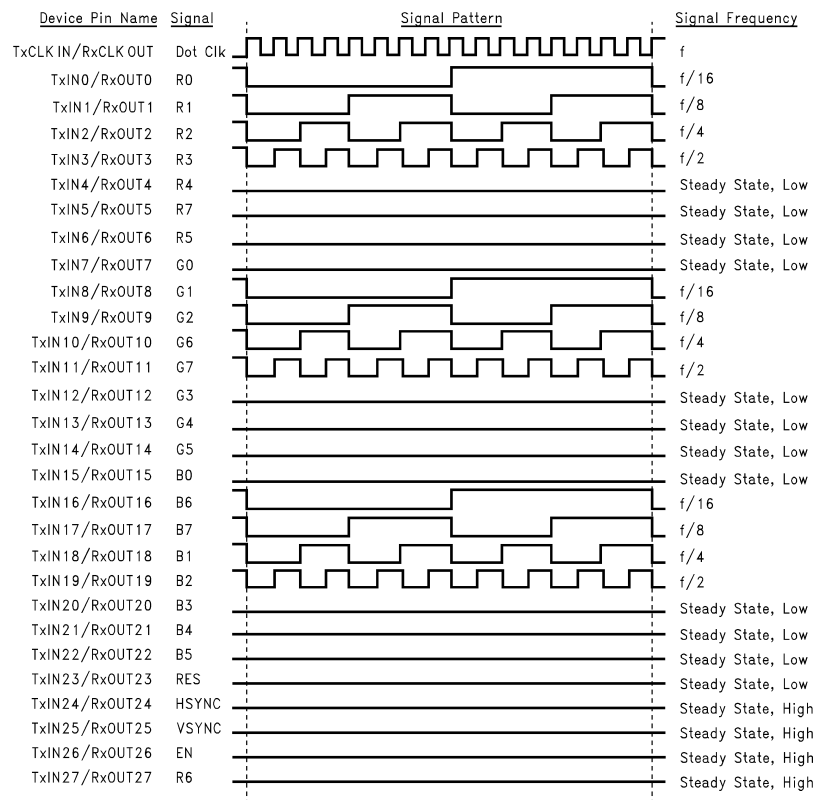
Symbol	Parameter		Min	Typ	Max	Units
CLHT	CMOS/TTL Low-to-High Transition Time (Figure 4 )			2	5	ns
CHLT	CMOS/TTL High-to-Low Transition Time (Figure 4)			1.8	5	ns
RSPos0	Receiver Input Strobe Position for Bit 0 (Figure 10)	f = 25 MHz	1.20	1.96	2.82	ns
RSPos1	Receiver Input Strobe Position for Bit 1		6.91	7.67	8.53	ns
RSPos2	Receiver Input Strobe Position for Bit 2		12.62	13.38	14.24	ns
RSPos3	Receiver Input Strobe Position for Bit 3		18.33	19.09	19.95	ns
RSPos4	Receiver Input Strobe Position for Bit 4		24.04	24.80	25.66	ns
RSPos5	Receiver Input Strobe Position for Bit 5		29.75	30.51	31.37	ns
RSPos6	Receiver Input Strobe Position for Bit 6		35.46	36.22	37.08	ns
RSPos0	Receiver Input Strobe Position for Bit 0 (Figure 10)	f = 65 MHz	0.7	1.1	1.4	ns
RSPos1	Receiver Input Strobe Position for Bit 1		2.9	3.3	3.6	ns
RSPos2	Receiver Input Strobe Position for Bit 2		5.1	5.5	5.8	ns
RSPos3	Receiver Input Strobe Position for Bit 3		7.3	7.7	8.0	ns
RSPos4	Receiver Input Strobe Position for Bit 4		9.5	9.9	10.2	ns
RSPos5	Receiver Input Strobe Position for Bit 5		11.7	12.1	12.4	ns
RSPos6	Receiver Input Strobe Position for Bit 6		13.9	14.3	14.6	ns
RSKM	RxIN Skew Margin <sup>(1)</sup> (Figure 11)	f = 25 MHz	750			ps
		f = 65 MHz	500			ps
RCOP	RxCLK OUT Period (Figure 5)		15	T	50	ns
RCOH	RxCLK OUT High Time (Figure 5)	f = 65 MHz	5.0	7.6	9.0	ns
RCOL	RxCLK OUT Low Time (Figure 5)		5.0	6.3	9.0	ns
RSRC	RxOUT Setup to RxCLK OUT (Figure 5)		4.5	7.3		ns
RHRC	RxOUT Hold to RxCLK OUT (Figure 5)		4.0	6.3		ns
RCCD	RxCLK IN to RxCLK OUT Delay @ 25°C, V <sub>CC</sub> = 3.3V (Figure 6)		3.5	5.0	7.5	ns
RPLLS	Receiver Phase Lock Loop Set (Figure 7)				10	ms
RPDD	Receiver Power Down Delay (Figure 9)				1	μs

(1) Receiver Skew Margin is defined as the valid data sampling region at the receiver inputs. This margin takes into account the DS90C383B transmitter pulse positions (min and max) and the receiver input setup and hold time (internal data sampling window - RSPos). The RSKM will change when different transmitters are used. This margin allows for LVDS interconnect skew, inter-symbol interference (both dependent on type/length of cable), and clock jitter (less than 250 ps).

**AC Timing Diagrams**



**Figure 2. “Worst Case” Test Pattern**

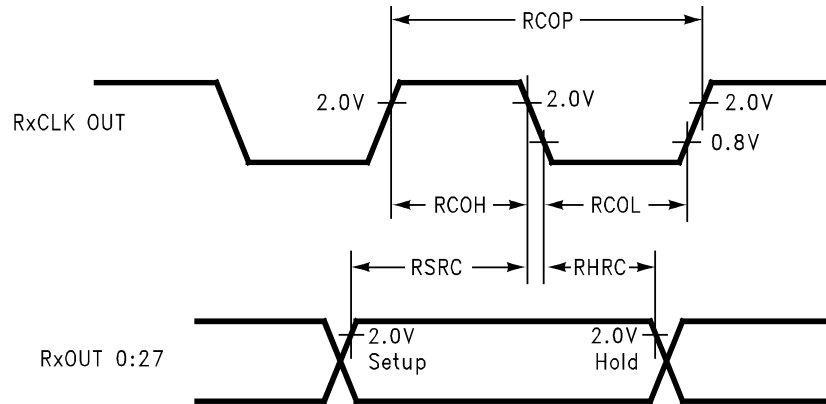


The worst case test pattern produces a maximum toggling of digital circuits, LVDS I/O and CMOS/TTL I/O. The 16 grayscale test pattern tests device power consumption for a “typical” LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical stripes across the display. [Figure 2](#) and [Figure 3](#) show a falling edge data strobe (TxCLK IN / RxCLK OUT). Recommended pin to signal mapping. Application may choose to define differently, check compatibility with source.

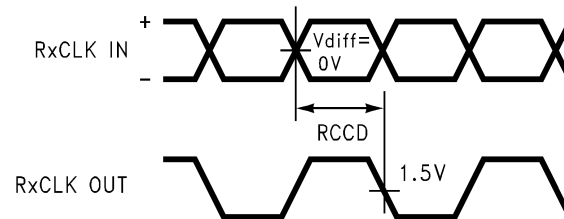
**Figure 3. “16 Grayscale” Test Pattern**



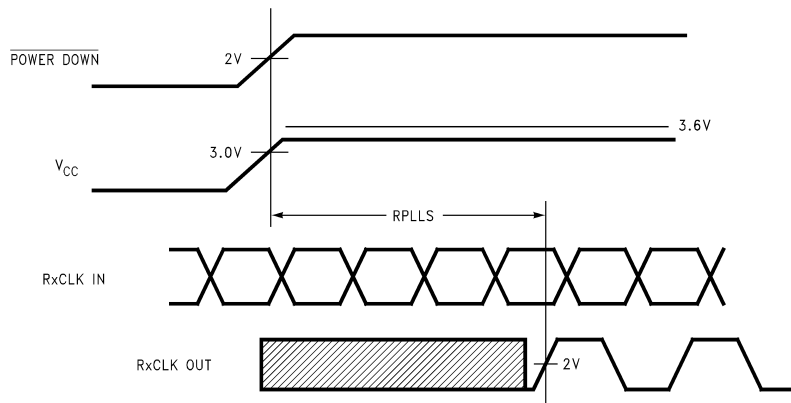
**Figure 4. Receiver CMOS/TTL Output Load and Transition Times**



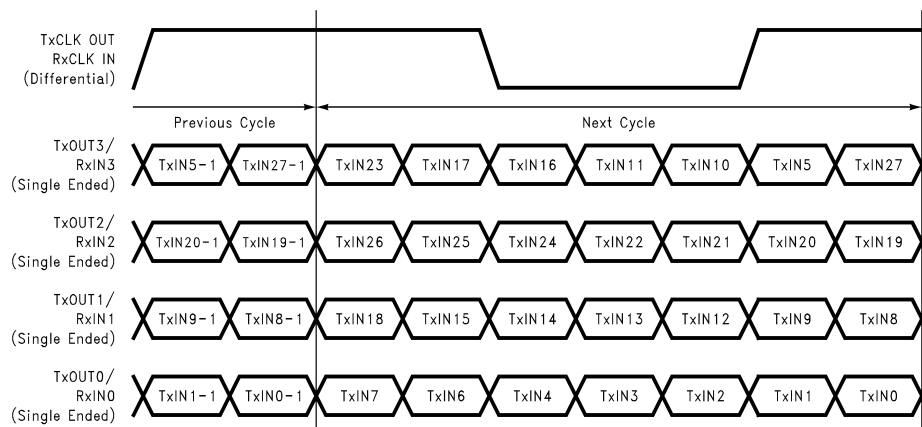
**Figure 5. Receiver Output Setup/Hold and High/Low Times**



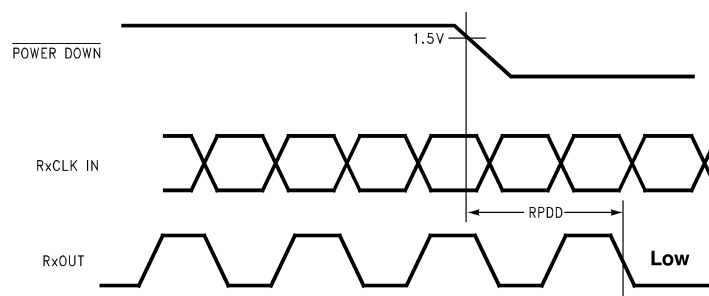
**Figure 6. Receiver Clock In to Clock Out Delay**



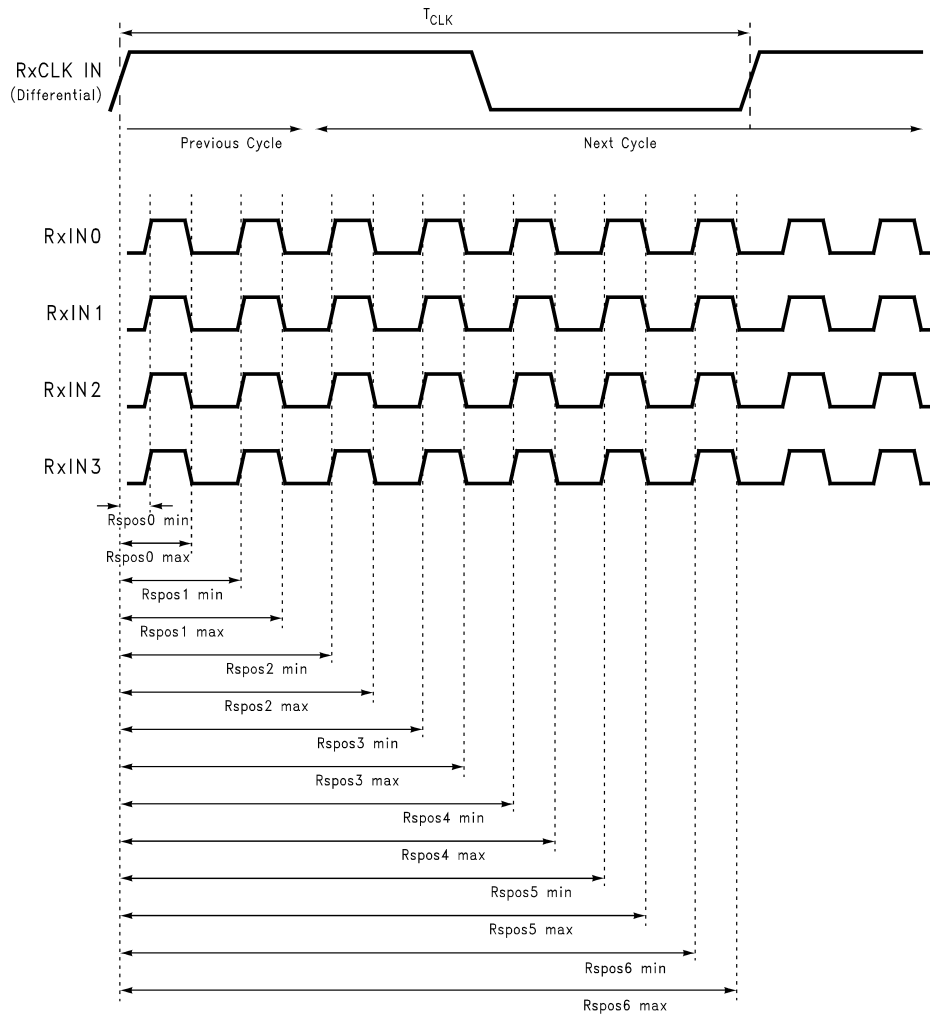
**Figure 7. Receiver Phase Lock Loop Set Time**



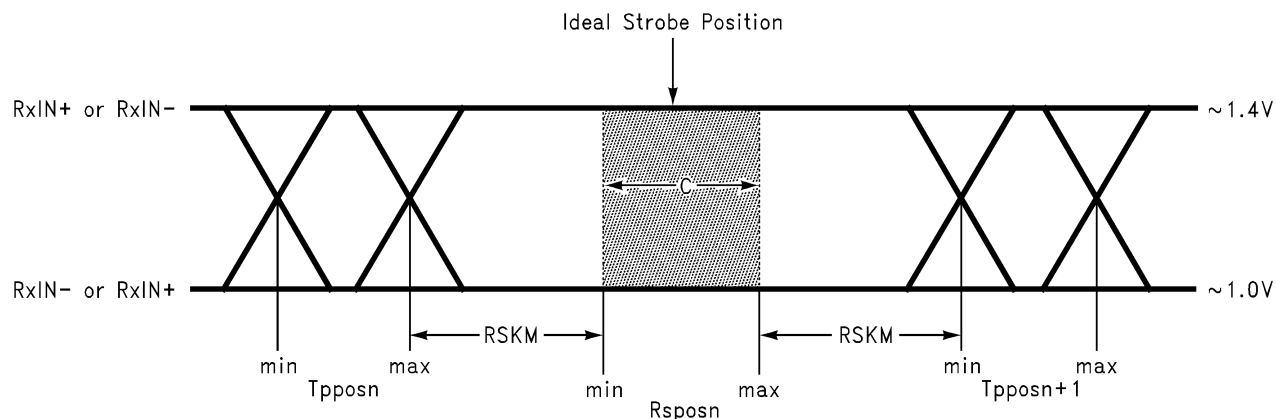
**Figure 8. 28 Parallel TTL Data Inputs/Outputs Mapped to LVDS Bits (TxINn / RxOUTn)**



**Figure 9. Receiver Power Down Delay**



**Figure 10. Receiver LVDS Input Strobe Position**



C—Setup and Hold Time (Internal data sampling window) defined by Rspos (receiver input strobe position) min and max

Tppos—Transmitter output pulse position (min and max)

RSKM = Cable Skew (type, length) + Source Clock Jitter (cycle to cycle) + ISI (Inter-symbol interference)

Cable Skew—typically 10 ps–40 ps per foot, media dependent

Cycle-to-cycle jitter is less than 250 ps at 65 MHz.

ISI is dependent on interconnect length; may be zero.

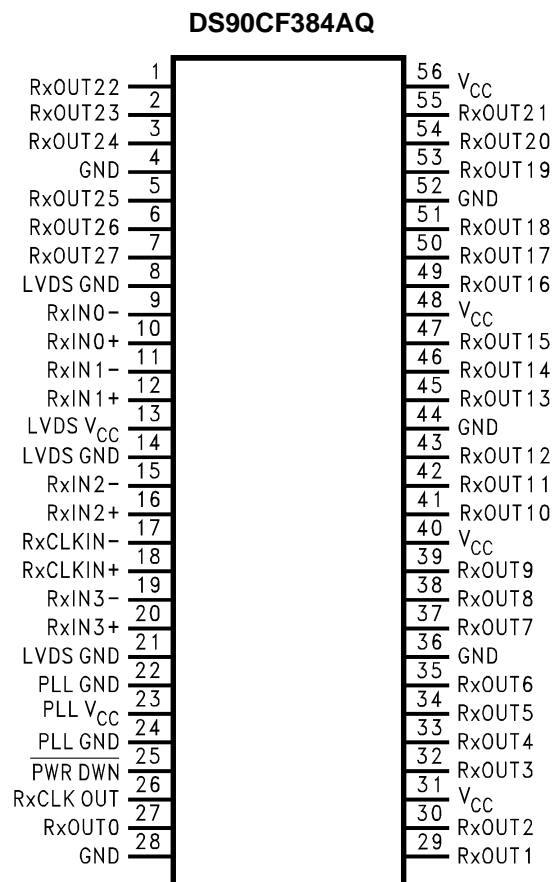
**Figure 11. Receiver LVDS Input Skew Margin**

## DS90CF384AQ Pin Descriptions — 56L TSSOP Package

Pin Name	I/O	No.	Description
RxIN+	I	4	Positive LVDS differential data inputs.
RxIN–	I	4	Negative LVDS differential data inputs.
RxOUT	O	28	TTL level data outputs. This includes: 8 Red, 8 Green, 8 Blue, and 3 control lines—FPLINE, FPFRAME, DRDY (also referred to as HSYNC, VSYNC, Data Enable).
RxCLK IN+	I	1	Positive LVDS differential clock input.
RxCLK IN–	I	1	Negative LVDS differential clock input.
RxCLK OUT	O	1	TTL level clock output. The falling edge acts as data strobe.
PWR DOWN	I	1	TTL level input. When asserted (low input) the receiver outputs are low.
V <sub>CC</sub>	I	4	Power supply pins for TTL outputs.
GND	I	5	Ground pins for TTL outputs.
PLL V <sub>CC</sub>	I	1	Power supply for PLL.
PLL GND	I	2	Ground pin for PLL.
LVDS V <sub>CC</sub>	I	1	Power supply pin for LVDS inputs.
LVDS GND	I	3	Ground pins for LVDS inputs.



## Pin Diagram for TSSOP Package



**Figure 12. 56-Lead TSSOP (DGG Package)**

REVISION HISTORY

Changes from Original (April 2013) to Revision A	Page
• Changed layout of National Data Sheet to TI format .....	<a href="#">9</a>

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">DS90CF384AQMT/NOPB</a>	Active	Production	TSSOP (DGG)   56	34   TUBE	Yes	SN	Level-2-260C-1 YEAR	-40 to 85	DS90CF384AQ MT
DS90CF384AQMT/NOPB.B	Active	Production	TSSOP (DGG)   56	34   TUBE	Yes	SN	Level-2-260C-1 YEAR	-40 to 85	DS90CF384AQ MT
<a href="#">DS90CF384AQMTX/NOPB</a>	Active	Production	TSSOP (DGG)   56	1000   LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 85	DS90CF384AQ MT

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS90CF384AQMXX/ NOPB	TSSOP	DGG	56	1000	330.0	24.4	8.6	14.5	1.8	12.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS90CF384AQMTX/NOPB	TSSOP	DGG	56	1000	356.0	356.0	45.0

## TUBE



\*All dimensions are nominal

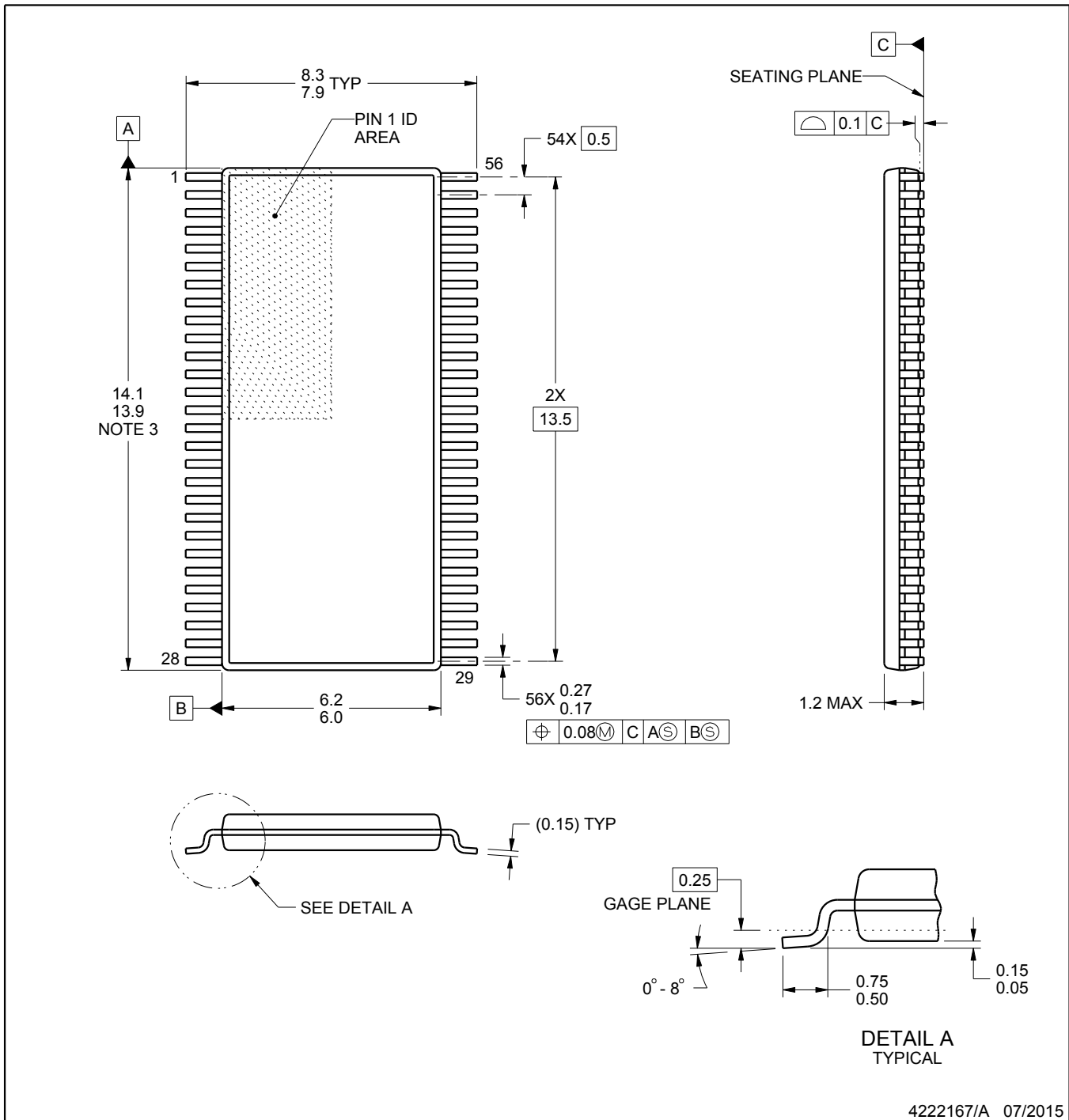
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS90CF384AQMT/NOPB	DGG	TSSOP	56	34	495	10	2540	5.79
DS90CF384AQMT/ NOPB.B	DGG	TSSOP	56	34	495	10	2540	5.79

DGG0056A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4222167/A 07/2015

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

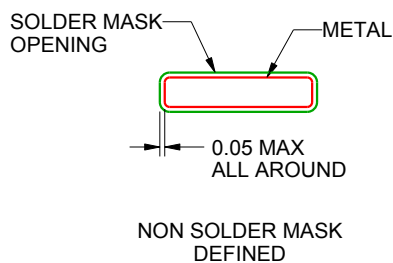
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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